

B¹ concl'd
¹ (Amended) An electronic chip device comprising an interface support film including a support film and at least one flat conductive interface placed on the support film, said interface support film having such properties that it is capable of being creased or folded over onto itself without deterioration, and a microcircuit connected to the interface, wherein the support film and the interface can be creased or folded together with a curve radius of less than 2.5 mm without deterioration.

B²
³ (Amended) The device according to claim ² ~~3~~, wherein the encapsulating material is contained at least partly by said recess.

B²
¹⁹ (Amended) An electronic chip device comprising an interface support film including a support film and at least one flat conductive interface placed on the support film, said interface support film having such properties that it is capable of being creased or folded over onto itself without deterioration, and a microcircuit connected to the interface, wherein the support film has a thickness of less than 75 μm .

B³
⁴ (Amended) The device according to claim ¹ ~~4~~, wherein the support film has at least one of an elongation at break of more than 80%, a Shore hardness of less than 80, a vitreous transition temperature T_g of less than 0°, and a fusion temperature of less than 130°C.

⁶
~~10~~. (Amended) The device according to claim ¹~~4~~, wherein the support film is made from a material selected from the group comprising PP, PE and PET.

B3
concluded
⁷
~~11~~. (Amended) The device according to claim ¹~~4~~, wherein the interface is aluminum.

⁸
~~12~~. (Amended) The device according to claim ¹~~4~~, wherein the interface comprises turns of conductive material and the microcircuit is placed outside the turns.

B4
¹²
~~13~~. (Twice Amended) An electronic chip device comprising an interface support film including a support film and at least one flat conductive interface placed on the support film, said interface support film having such properties that it is capable of being creased or folded over onto itself without deterioration, and a microcircuit connected to the interface, further including a strap on the face of the film opposite the microcircuit to pull back at least one end of the interface in the vicinity of the microcircuit.

22
14.

(Twice Amended) An electronic chip device comprising an interface support film including a support film and at least one flat conductive interface placed on the support film, said interface support film having such properties that it is capable of being creased or folded over onto itself without deterioration, and a microcircuit connected to the interface, wherein the interface comprises an antenna having turns of conductive material and wherein the width of the turns around the microcircuit are thinner than elsewhere in such a way as to directly connect the microcircuit to ends of the interface with a small length of connecting wire.

23
15.

(Twice Amended) An electronic chip device comprising an interface support film including a support film and at least one flat conductive interface placed on the support film, said interface support film having such properties that it is capable of being creased or folded over onto itself without deterioration, and a microcircuit connected to the interface, wherein the interface comprises an antenna having turns of conductive material and wherein the microcircuit is placed between the turns directly over the support film.

9
16.

(Amended) The device of claim 1, wherein the interface comprises turns of conductive material and the microcircuit is placed in a corner of the support film and directly above the support film.

B5
concl'd

10.
17.

(Amended) The device according to claim ~~4~~¹, wherein the interface has at least one antenna turn formed in such a way as to be able to communicate over a distance of more than 8 cm.

12.
19.

(Amended) The device according to claim ~~4~~¹, wherein the interface has connection pads.

B6

13.
20.

(Amended) The device according to claim ~~4~~¹, further including an encapsulating material over at least the microcircuit, its connections and a portion of the interface.

14.
21.

(Amended) The device according to claim ~~4~~¹, further including at least one of a protection/personalization film and an adhesive film over at least one of the faces of the device.

15.
22.

(Amended) The device according to claim ~~4~~¹, further including a resonance capacitor made up of two conductive plates placed on respective sides of the support film.

B7

17.
24.

(Amended) The device according to claim ~~4~~¹, wherein the microcircuit contains at least one of an integrated capacitor and an emergency antenna.

B8
²⁶~~27~~ (Amended) The chip card of claim ²⁴~~48~~, wherein said card body has an area which is at least double that of said electronic chip device.

²⁶~~28~~ (Amended) The chip card of claim ²⁴~~48~~, comprising two external films between which the electronic chip device is sandwiched.

B9
²⁸~~30~~ (Amended) The chip card of claim ²⁴~~48~~, wherein said card body has a cavity and the microcircuit is located in the cavity, and wherein the support film and the interface extend outside the cavity over the surface of the card body.

²⁴~~48~~ (Amended) A chip card comprising a card body on which an electronic chip device is fixed, the card body having an area greater than or equal to that of the device, said electronic chip device comprising an interface support film including a support film and at least one flat conductive interface placed on the support film, said interface support film having such properties that it is capable of being creased or folded over onto itself without deterioration, and a microcircuit connected to the interface, wherein the support film and the interface can be folded with a radius of curvature less than 2.5 mm without deterioration.

B11
³¹~~50~~ (Amended) A chip card comprising a card body on which an electronic chip device is fixed, the card body having an area greater than or equal to that of the device, said electronic chip device comprising an interface support film including a support film

B11
concl'd

and at least one flat conductive interface placed on the support film, said interface support film having such properties that it is capable of being creased or folded over onto itself without deterioration, and a microcircuit connected to the interface, wherein said support film has a thickness less than 75 μm .

B12

²⁹
52. (Amended) The chip card of claim ²⁴~~48~~, wherein the support film has at least one of an elongation at break of more than 80%, a Shore hardness of less than 80, a vitreous transition temperature T_g of less than 0°, and a fusion temperature of less than 130°C.

⁴⁰
60. (Amended) An electronic chip device comprising:

B13

an interface support film including a support film and at least one communication interface formed by plural turns of a conductive material on the support film;

a microcircuit connected to the interface;

and a compensation film on the support film, said compensation film having a recess containing said microcircuit, its connections and an encapsulating material, wherein the interface support film including the communication interface and the support film can be folded or creased over onto itself without deterioration.
